

MAXIMUM SOLUTIONS

Mill-Max USB Connectors



Standard USB Features

- USB receptacles for through-hole & SMT.
- Plug retention tabs.
- Kinked locating legs for secure PCB retention.
- Fully compatible with USB 1.0 & 2.0 specifications.
- Passes 16MHz Signal Attenuation per ASTM-D-4566.
- Packaged in trays, 150 pieces per tray.

Mini USB Features

- Mini USB receptacles for surface mount.
- 5 Pin (one ID Pin), 0.8mm pitch, mini USB connector.
- Reduced mounting space.
- Fully compliant with current USB 2.0 specifications.
- Smaller and lighter than existing USB connectors for portable and handheld devices.
- Packaged on Tape & Reel -- 700 parts per reel.

For more information, please visit: www.mill-max.com

(5/14 -- PR589)

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SERIES 896, 897 • UNIVERSAL SERIAL BUS • SOCKETS

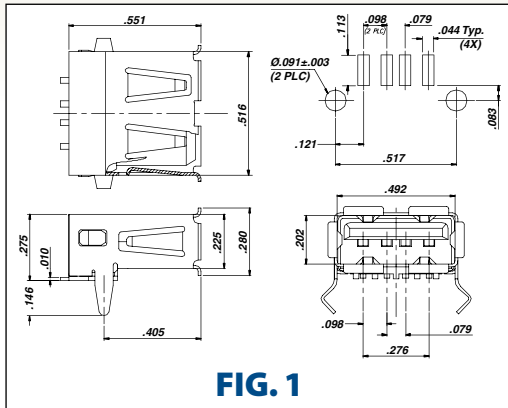


FIG. 1

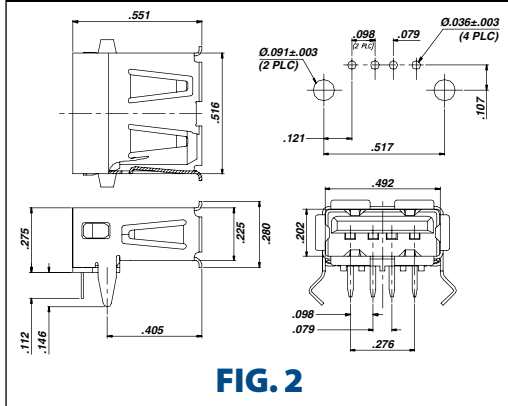


FIG. 2

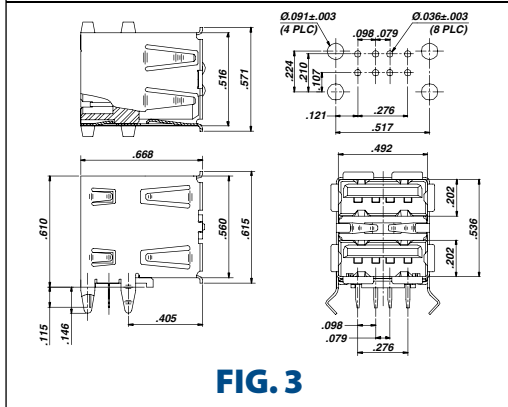


FIG. 3

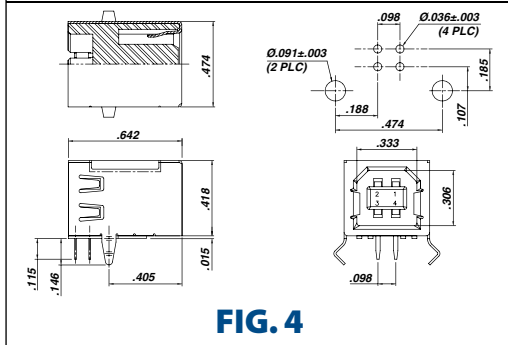


FIG. 4

- USB receptacles for through-hole and surface mount
- Plug retention tabs
- Kinked locating legs for secure PCB retention
- Fully shielded
- Fully compatible with USB 1.0 and 2.0 specifications
- Passes 16MHz signal attenuation per ASTM-D-4566
- Packaged in trays, 150 pieces per tray



ORDERING INFORMATION

FIG. 1	Type A Receptacle, Single, Surface Mount
	896-43-004-00-000000
FIG. 2	Type A Receptacle, Single, Through-Hole
	896-43-004-90-000000
FIG. 3	Type A Receptacle, Double, Through-Hole
	896-43-008-90-000000
FIG. 4	Type B Receptacle, Single, Through-Hole
	897-43-004-90-000000

Technical Specifications

Materials:

Terminals: Copper Alloy, Tin-Plated
 Casing and Shield: Stainless Steel
 Insulator material: High temperature thermoplastic rated UL94V-0

Ratings:

Voltage: 30VAC (rms)
 Current: 1A max. per contact for 30°C temperature rise
 All housing materials rated for "lead-free" soldering up to 260° C

Electrical:

Contact resistance: 30mΩ max.
 Insulation resistance: 1000MΩ min.
 Dielectric withstanding voltage: 750VAC at sea level
 Capacitance: 2pF max.

Mechanical:

Random vibration: No discontinuity >1μs per EIA 364-28, cond. V, letter A
 Physical shock: No discontinuity >1μs per EIA 364-27, condition H
 Durability: 1500 cycles min. per EIA 364-09
 Mating force: 35 Newtons max. per EIA 364-13
 Unmating force: 10 Newtons min. per EIA 364-13

Environmental:

Thermal shock per EIA 364-32, condition I
 Humidity per EIA 364-31, method II, condition A
 Temperature life per EIA 364-17, condition 3, method A



SERIES 896, 897 • MINI UNIVERSAL SERIAL BUS • SURFACE MOUNT SOCKETS

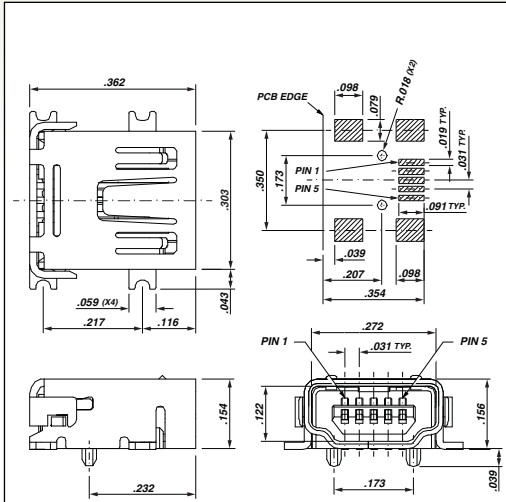


FIG. 1

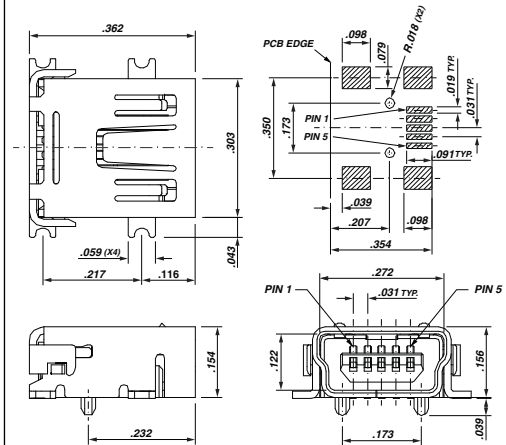


FIG. 2

- Mini USB receptacles for surface mount
- 5 Pin (one ID Pin), 0.8mm pitch, mini USB connector
- Reduced mounting space
- Fully Shielded
- Fully compliant with current USB 2.0 specifications
- Smaller and lighter than standard USB connectors for portable & handheld devices
- Packaged on Tape & Reel - 700 pieces per reel



ORDERING INFORMATION

FIG. 1	Mini Type A Receptacle, Single, Surface Mount
	896-43-005-00-100001
FIG. 2	Mini Type B Receptacle, Single, Surface Mount
	897-43-005-00-100001

Technical Specifications

Materials:

Terminals: Copper Alloy, Tin Plated
 Contacts: Copper Alloy, 30 μ " Gold Plated
 Casing and Shield: Stainless Steel
 Insulator material: High temperature thermoplastic rated UL94V-0



Ratings:

Voltage: 30VAC (rms)
 Current: 1A max. per contact for 30°C temperature rise
 All housing materials rated for "lead-free" soldering up to 260° C

Electrical:

Contact resistance: 50m Ω max.
 Insulation resistance: 100M Ω min.
 Dielectric withstanding voltage: 100VAC at sea level
 Capacitance: 2pF max.

Mechanical:

Random vibration: No discontinuity >1 μ s per EIA 364-28, cond. V, letter A
 Physical shock: No discontinuity >1 μ s per EIA 364-27, condition H
 Durability: 5000 cycles min. per EIA 364-09
 Mating force: 35 Newtons max. per EIA 364-13
 Unmating force: Initial - 7 Newtons min. per EIA 364-13
 After test - 3 Newtons min. per EIA 364-13
 Cable pull-out force per EIA 364-38

Environmental:

Thermal shock per EIA 364-32, condition I
 Humidity per EIA 364-31, method II, condition A
 Temperature life per EIA 364-17, condition 3, method A
 Solderability per EIA 364-52, category 2